**JSR Dielectric Materials**

- Buffer coat, RDL dielectrics
- **WPR series**
- RDL in high density wiring
- **FG series**
- Low Df polymer for Substrate
- **HC polymer**

### WPR series

<table>
<thead>
<tr>
<th>After Dev.</th>
<th>After Cure</th>
</tr>
</thead>
<tbody>
<tr>
<td>Positive-tone</td>
<td>Positive-tone</td>
</tr>
<tr>
<td>FT=6 μm, 20 μm SQ</td>
<td>FT=2 μm, 3 μm SQ</td>
</tr>
</tbody>
</table>

**Key Features**

- Low cure temperature (200 °C)
- Low Shrinkage through cure (< 10 %)
- Low residual stress (< 20 MPa)
- High resolution
- Excellent adhesion to SiN, SiO₂ and Cu
- Excellent heat resistance
- Long history for global customers

### FG series

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<td>Positive-tone</td>
</tr>
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</tr>
</tbody>
</table>

**Key Features +**

- Lower Dk (2.9@10 GHz)
- Lower water absorption
- Higher resolution (2 μm-SQ)

### HC polymer

**Key Features**

- Low Df (< 0.002)
- High heat-resistance
- Good compatibility with chemicals
- Good adhesion